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# U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM 10015374	FILING DATE 12/12/2001	CLASS 257	SUBCLASS 685	GAU 28	EXAMINER William J.
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\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:  
REPUBLIC OF KOREA 2001-12326 03/09/2001

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no  
35 USC 119 conditions met ☐ yes ☐ no  
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO  
W2K1070

TITLE : Stacking structure of semiconductor chips and semiconductor package using it

U.S. DEPT. OF COMM. / PAT. & TM-PTO-136L (Rev. 12-94)

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Assistant Examiner	Total Claims Print Claim for O.G.
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drawn	Figs. Drawn Print Figs.
		Primary Examiner	Application Examiner
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>PREPARED FOR ISSUE</b> <b>WARNING:</b> The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181, and 368; Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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